

### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

C	haracteristic	Symbol	Value	Unit
Drain Source Voltage		$V_{DSS}$	50	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Drain Current (Note 5)	Continuous Pulsed (Note 6)	I <sub>D</sub>	300 800	mA

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	$P_{D}$	350	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

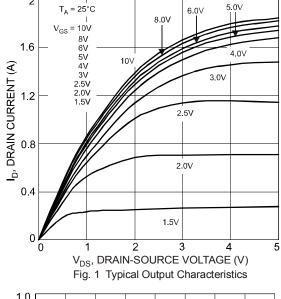
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage		$BV_{DSS}$	50	_	_	V	$V_{GS} = 0V, I_D = 10\mu A$	
Zero Gate Voltage Drain Current	@ T <sub>C</sub> = +25°C	I <sub>DSS</sub>		_	60	nA	$V_{DS} = 50V, V_{GS} = 0V$	
Gate-Body Leakage		I <sub>GSS</sub>	_	_	1 500 50	μΑ nA nA	$V_{GS} = \pm 12V, V_{DS} = 0V$ $V_{GS} = \pm 10V, V_{DS} = 0V$ $V_{GS} = \pm 5V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage		$V_{GS(th)}$	0.49	_	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		R <sub>DS(ON)</sub>		_	3.0 2.5	Ω	$V_{GS} = 1.8V, I_D = 50mA$ $V_{GS} = 2.5V, I_D = 50mA$	
State Brain Source on redistance		TVDS(ON)		_	2.0	32	$V_{GS} = 5.0V$ , $I_D = 50mA$	
On-State Drain Current		I <sub>D(ON)</sub>	0.5	1.4	_	Α	$V_{GS} = 10V, V_{DS} = 7.5V$	
Forward Transconductance		Y <sub>fs</sub>	200	_	_	mS	$V_{DS} = 10V, I_D = 0.2A$	
Source-Drain Diode Forward Voltage		$V_{SD}$	0.5	_	1.4	V	$V_{GS} = 0V, I_{S} = 115mA$	
DYNAMIC CHARACTERISTICS								
Input Capacitance		C <sub>iss</sub>	_	_	50	pF	\\ OE\\\\\	
Output Capacitance		Coss	_	_	25	pF	$V_{DS} = 25V, V_{GS} = 0V$ - f = 1.0MHz	
Reverse Transfer Capacitance		C <sub>rss</sub>	_	_	5.0	pF		

Notes:

- 5. Device mounted on FR-4 PCB
- 6. Pulse width ≤10mS, Duty Cycle ≤1%.
  7. Short duration pulse test used to minimize self-heating effect.





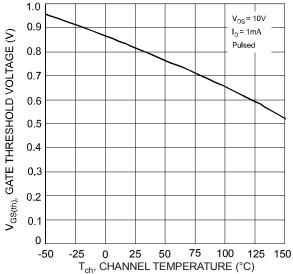


Fig. 3 Gate Threshold Voltage vs. Channel Temperature

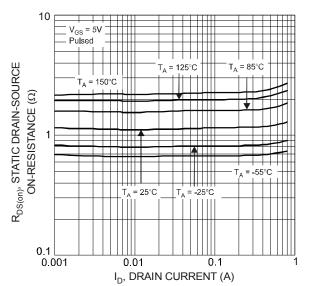
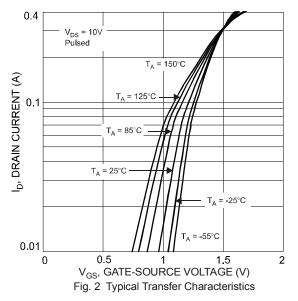


Fig. 5 Static Drain-Source On-Resistance vs. Drain Current



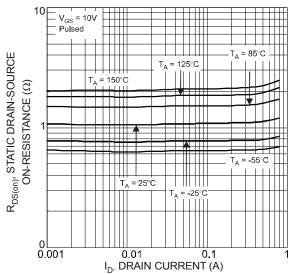


Fig. 4 Static Drain-Source On-Resistance vs. Drain Current

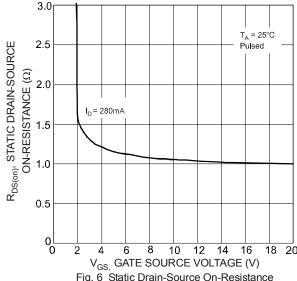


Fig. 6 Static Drain-Source On-Resistance vs. Gate-Source Voltage



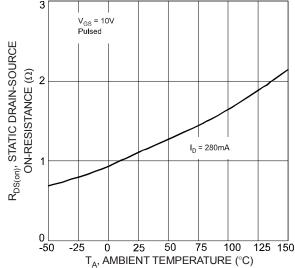


Fig. 7 Static Drain-Source On-State Resistance vs. Ambient Temperature

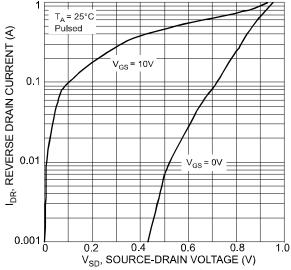
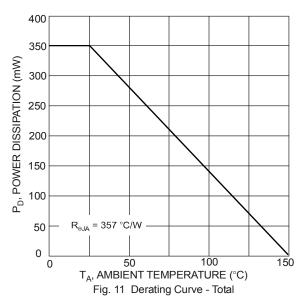


Fig. 9 Reverse Drain Current vs. Source-Drain Voltage



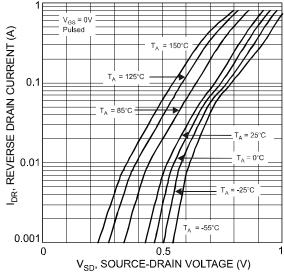


Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

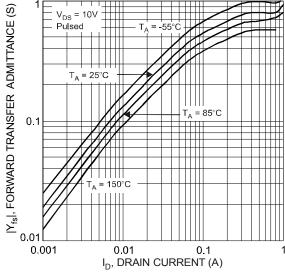
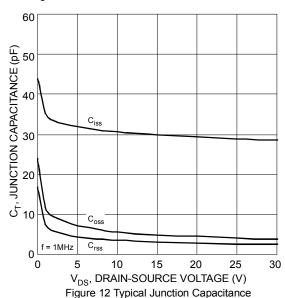


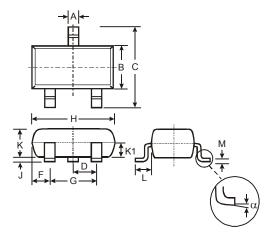
Fig. 10 Forward Transfer Admittance vs. Drain Current





### **Package Outline Dimensions**

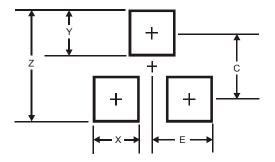
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23				
Dim	Min	Max	Тур	
Α	0.37	0.51	0.40	
В	1.20	1.40	1.30	
С	2.30	2.50	2.40	
D	0.89	1.03	0.915	
F	0.45	0.60	0.535	
G	1.78	2.05	1.83	
Н	2.80	3.00	2.90	
J	0.013	0.10	0.05	
K	0.903	1.10	1.00	
K1	-	-	0.400	
L	0.45	0.61	0.55	
M	0.085	0.18	0.11	
α	0°	8°	-	
All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)				
Z	2.9				
X	0.8				
Υ	0.9				
C	2.0				
F	1 35				



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